



PRODUCT DATASHEET



- SuperFlux (Piranha)
- ► 5mm Round 5.05t
- Red (630nm)

SuperFlux 5mm



FEATURES:

- Package: PTH Through Hole 4-Pins Package
- Forward Current: 20mA
- Forward Voltage (typ.): 2.1V
- Luminous Intensity (typ.): 1800mcd@20mA .
- Colour: Red .
- Wavelength: 630nm .
- Viewing angle: 85° •
- Materials:
 - Die: AlGaInP/GaP _
 - _ Resin: Epoxy (Water Clear)
 - _ L/T Finish: Ag plated
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C .
- ESD (HBM): 2000V
- **Grouping parameters:** •
 - Forward voltage _
 - _ Luminous intensity
 - **Dominant Wavelength** _
- Soldering methods: Wave Soldering
- MSL: acc. to JEDEC Level 3
- Packing: 60pcs/tube; 6300pcs/carton



NOR18P68S

APPLICATIONS:

- Indicator .
- Signal Light
- SuperFlux 5mm



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	lF	70	mA
Pulse Forward Current Duty 1/10 at 10KHz	IPF	100	mA
Power Dissipation	PD	130	mW
Reverse Current @5V	IR	10	μΑ
Electrostatics Discharge (HBM)	ESD	2000	V
Operating Temperature	Topr	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

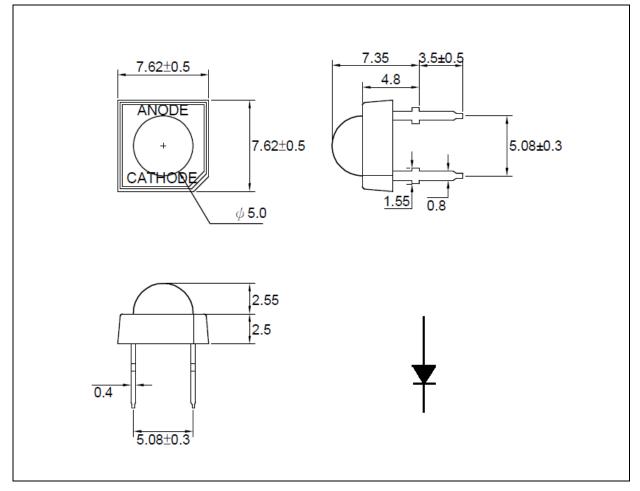
Parameter	Symbol	Values			Unit	Test
		Min.	Тур.	Max.	Unit	Condition
Forward Voltage	VF	1.7		2.6	V	I⊧=20mA
Luminous Intensity	Iv	900	1800		mcd	I _F =20mA
Dominant Wavelength	λ_{D}		630		nm	I⊧=20mA
Spectral Half Width	Δλ		20		nm	I _F =20mA
Viewing Angle	2 θ 1/2		85		deg	I⊧=20mA

1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2 $\theta_{1/2}$) ±5%



OUTLINE DIMENSION:

Package Dimension:

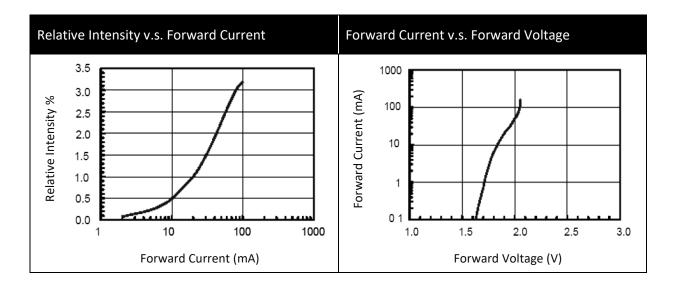


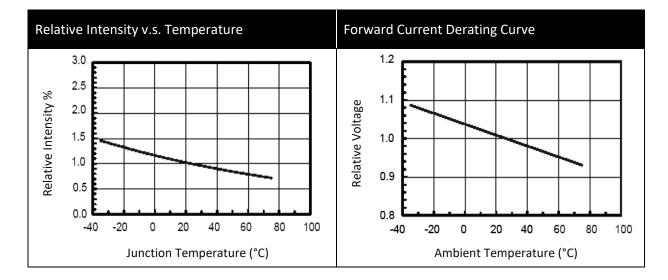
- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

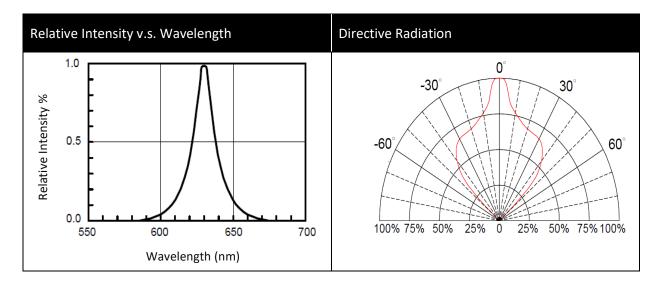
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ELECTRO-OPTICAL CHARACTERISTICS:





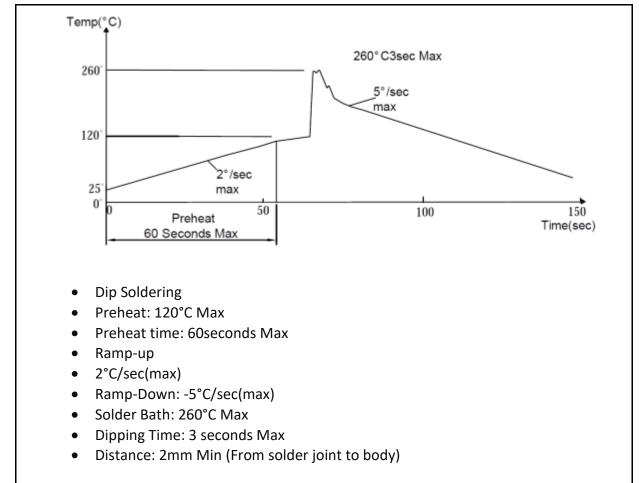




DIP Iron:

- Soldering Iron 30W Max.
- Temperature 350°C Max.
- Soldering Time 3 seconds Max. One time only.
- Distance 2mm Min. (from solder joint to body).

Wave Soldering Profile:



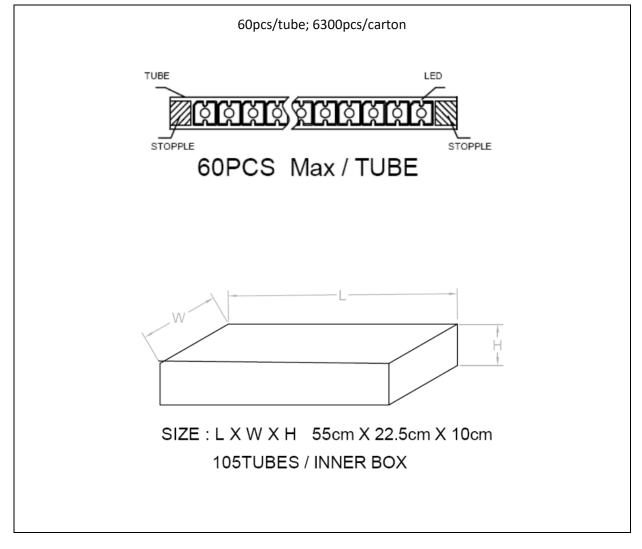
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.
- 3. Recommended reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.



PACKING SPECIFICATION:

Tube Dimension:



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PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

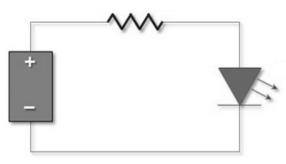
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 6hrs and <5%RH, for reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	06/07/2015	Datasheet set-up.
A1.1	26/06/2022	Add -S ending.